

ABSTRACT

A power semiconductor module with a connection structure in which an electrode terminal whose one end is connected with an electric power semiconductor device which is resin sealed inside of the case, is exposed along an outer surface of a case for taking out electrode from the semiconductor device, and is electrically connected to an electrode for external connection disposed on the electrode terminal, wherein a female screw hole for screwing is provided on side of the outer surface of the case, a male screw member formed at its opposite ends with screw threads is threadedly engaged with the female screw hole through the electrode terminal.